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Tracking the Development of Structural Bonding in Composite Repairs during Curing

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A novel structural assessment technique for composite bonded repairs of metallic structures is introduced, using embedded fiber optic Bragg sensors. By utilizing the large difference in the thermal expansion coefficients between the composite patch and the Aluminum substrate, the tracking of both the curing process and bonding quality is now made possible for both room and elevated temperature cure adhesives.

Ключевые слова:

Содержание.

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